

SAFE GUARDS

SGS-CSTC

欧盟 RoHS 指令豁免条款

截止到 2005 年 10 月 25 日, 已通过欧委会批准并正式公布的 RoHS 豁免项

2002/95/EC 附录上的十条

免除第 4 (1) 条中所要求的铅、汞、镉和六价铬的应用

1. 小型日光灯中的汞含量不得超过 5 毫克/灯;
2. 一般用途的直管日光灯中的汞含量不得超过:
 - 盐磷酸盐 10 毫克
 - 正常的三磷酸盐 5 毫克
 - 长效的三磷酸盐 8 毫克
3. 特殊用途的直管日光灯中的汞含量;
4. 本附录中未特别提及的其它照明灯中的汞含量;
5. 阴极射线管、电子部件和发光管的玻璃内的铅含量;
6. 钢中合金元素中的铅含量达 0.35%、铝含量达 0.4%, 铜合金中的铅含量达 4%;
7. -- 高温融化的焊料中的铅 (即: 锡铅焊料合金中铅含量超过 85%);
 - 用于服务器、存储器和存储系统的焊料中的铅 (豁免准予至 2010 年);
 - 用于交换、信号和传输, 以及电信网络管理的网络基础设施设备中焊料中的铅;
 - 电子陶瓷产品中的铅 (例如: 高压电子装置);*(该项在 2005/747/EC 中作了修改, 详见下页)*
8. 根据修改关于限制特定危险物质和预制品销售和使用的第 76/769/EEC 号指令的第 91/338/EEC 号指令禁止以外的镉电镀。*(该项在 2005/747/EC 中作了修改, 详见下页)*
9. 在吸收式电冰箱中作为碳钢冷却系统防腐剂的六价铬。
10. 根据在第 7 (2) 条中提及的程序, 欧盟委员会应评价以下方面的应用:
 - 十卡二苯醚 (Deca BDE);
 - 特殊用途的直管日光灯中的汞;
 - 以下用途中所使用的焊料中的铅: 服务器、存储器、用于交换和传输的网络基础设施、电信网络管理设备 (旨在设定本指令豁免部分的特定截止时间);
 - 灯泡。

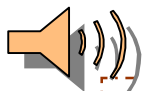
ANNEX

Applications of lead, mercury, cadmium and hexavalent chromium, which are exempted from the requirements of Article 4(1)

1. Mercury in compact fluorescent lamps not exceeding 5 mg per lamp.
2. Mercury in straight fluorescent lamps for general purposes not exceeding:
 - halophosphate 10 mg
 - triphosphate with normal lifetime 5 mg
 - triphosphate with long lifetime 8 mg.
3. Mercury in straight fluorescent lamps for special purposes.
4. Mercury in other lamps not specifically mentioned in this Annex.
5. Lead in glass of cathode ray tubes, electronic components and fluorescent tubes.
6. Lead as an alloying element in steel containing up to 0,35 % lead by weight, aluminium containing up to 0,4% lead by weight and as a copper alloy containing up to 4% lead by weight.
7. — Lead in high melting temperature type solders (i.e. tin-lead solder alloys containing more than 85 % lead),
 - lead in solders for servers, storage and storage array systems (exemption granted until 2010),
 - lead in solders for network infrastructure equipment for switching, signalling, transmission as well as network management for telecommunication,
 - lead in electronic ceramic parts (e.g. piezoelectronic devices).*(Point 7 is amended in 2005/747/EC.)*
8. Cadmium plating except for applications banned under Directive 91/338/EEC (*) amending Directive 76/769/EEC (**) relating to restrictions on the marketing and use of certain dangerous substances and preparations.*(Point 8 is amended in 2005/747/EC.)*
9. Hexavalent chromium as an anti-corrosion of the carbon steel cooling system in absorption refrigerators.
10. Within the procedure referred to in Article 7(2), the Commission shall evaluate the applications for:
 - Deca BDE,
 - mercury in straight fluorescent lamps for special purposes,
 - lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signalling, transmission as well as network management for telecommunications (with a view to setting a specific time limit for this exemption), and
 - light bulbs

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2005年10月13日正式公报最新豁免项目 (2005/717/EC)

- 2 Deca BDE in polymeric applications
十溴二苯醚在聚合物中的使用
- 2 lead in lead-bronze bearing shells and bushes
青铜轴瓦和衬套中的铅

2005年10月21日正式公报最新豁免项目 (2005/747/EC)

- 2 2002/95/EC 第7条修改如下:
 - Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead); 高温融化的焊料中的铅 (即: 铅含量≥85%的合金中的铅);
 - lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signalling, transmission as well as network management for telecommunication, 用于服务器、存储器和存储系统的焊料交换、信号和传输, 以及电信网络管理的网络基础设施设备中焊料中的铅;
 - lead in electronic ceramic parts (e.g. piezoelectric devices). 电子陶瓷产品中的铅 (例如: 高压电子装置) .
- 2 2002/95/EC 第8条修改如下:
Cadmium and its compounds in electrical contacts and cadmium plating except for applications banned under Directive 91/338/EEC (*) amending Directive 76/769/EEC (**) relating to restrictions on the marketing and use of certain dangerous substances and preparations.
电触点中的镉及镉化合物以及根据第 76/769/EEC 号指令修改的关于限制特定危险物质和预制品销售和使用的第 91/338/EEC 号指令禁止以外的镉镀层中的镉。

最新增加豁免项目

- 2 Lead used in compliant pin connector systems
顺应针联接系统中使用的铅
- 2 Lead as a coating material for the thermal conduction module c-ring
热导项枪钉模组(thermal conduction module c-ring)涂层中所用的铅
- 2 Lead and cadmium in optical and filter glass
光学玻璃及滤光玻璃中所用的铅及镉
- 2 lead in solders consisting of more than two elements for the connection between the pins and the package of microprocessors with a lead content of more than 80% and less than 85% by weight
微处理器引脚及封装联接所使用的含有 80-85%铅的复合 (含有超过两种组分) 焊料中的铅
- 2 lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages
倒装芯片(Flip chip)封装中半导体芯片及载体之间形成可靠联接所用焊料中的铅

确保您的产品顺利出口,



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